

ABSTRACT OF THE DISCLOSURE

There is provided a semiconductor device of a chip-on-chip structure having a support semiconductor chip, first and second chip blocks supported and connected on one surface of the support semiconductor chip and an insulator arranged between the first and second chip blocks. The first and second chip blocks each include one or a plurality of semiconductor chips having an active surface nearly parallel with the one surface of the support semiconductor chip. Within the insulator, an intralevel wiring is arranged on a wiring plane as a plane including an inactive or active surface of any of the semiconductor chips structuring the first or second chip block.